## fentures

- 300MHz to 6GHz Operating Frequency
- Wide IF Bandwidth: DC to 1GHz (-1dB Bandwidth)
- High Mixer IIP3: 30dBm at 1.9 GHz
- High Total OIP3: 40 dBm at 1.9 GHz
- High Total OIP2: 74dBm at 1.9 GHz
- User Adjustable OIP2 to 80dBm
- User Adjustable Image Rejection to 60dB
- User Adjustable DC Offset Null
- Serial Interface
- Power Conversion Gain: 7.7 dB at 1.9 GHz
- 31dB RF Attenuator with 1dB Step Size
- RF Switch with 40 dB Isolation at 1.9 GHz
- Single-Ended RF Inputs with On-Chip Transformer
- IF Amplifier Gain Adjustable in 8 Steps
- Operating Temperature Range $\left(\mathrm{T}_{\mathrm{C}}\right):-40^{\circ} \mathrm{C}$ to $105^{\circ} \mathrm{C}$
- 32-Lead $5 \mathrm{~mm} \times 5 \mathrm{~mm}$ QFN Package


## APPLICATIONS

- 4G and 5G Base Station Receivers
- Wideband DPD Receivers
- Point-To-Point Broadband Radios
- High Linearity Direct Conversion I/Q Receivers
- Image Rejection Receivers


## 6GHz High Linearity I/Q Demodulator with Wideband IF Amplifier DESCRIPTION

The LTC ${ }^{\circledR} 586$ is a direct conversion quadrature demodulator optimized for high linearity zero-IF and low IF receiver applications in the 300 MHz to 6 GHz frequency range. The very wide IF bandwidth of more than 1 GHz makes the LTC5586 particularly suited for demodulation of very wideband signals, especially in digital predistortion (DPD) applications. The outstanding dynamic range of the LTC5586 makes the device suitable for demanding infrastructure direct conversion applications. Proprietary technology inside the LTC5586 provides the capability to optimize OIP2 to 80dBm, and achieve image rejection better than 60 dB . The DC offset control function allows nulling of the DC offset at the A/D converter input, thereby optimizing the dynamic range of true zero-IF receivers that use DC coupled IF signal paths. The wideband RF and LO input ports make it possible to cover all the major wireless infrastructure frequency bands using a single device. The IF outputs of the LTC5586 are designed to interface directly with most common A/D converter input interfaces. The high OIP3 and high conversion gain of the device eliminate the need for additional amplifiers in the IF signal path.

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## TYPICAL APPLICATION

Dual Band Transmitter with DPD Receiver


Gain, OIP3 and OIP2 vs Temperature ( $\mathrm{T}_{\mathrm{C}}$ ) (Unoptimized)


## ABSOLUTE MAXIMUM RATINGS

(Note 1)
VCC, VCCN Supply Voltage (Note 21) ....... -0.3 V to 5.5 V
OVDD, SDO Voltage (Note 18).................. -0.3 V to 3.8 V
RFA, RFB DC Voltage ...................................1.5V to 2.0 V
LOP, LOM DC Voltage .................................2.1V to 2.8V
IFIM, IFIP, IFQP, IFQM DC Voltage ............. -0.3 V to 3.5 V
AIM, AIP, AQM, AQP
DC Voltage $\qquad$ $V_{C C}-1.7 \mathrm{~V}$ to $\mathrm{V}_{C C}-1.2 \mathrm{~V}$
MIM, MIP, MQM, MQP DC Voltage. $\qquad$ $\mathrm{V}_{\mathrm{CC}}-1.7 \mathrm{~V}$ to $\mathrm{V}_{\mathrm{CC}}-1.2 \mathrm{~V}$
Voltage on Any Other Pin $\qquad$ -0.3 V to 5.5 V
LOP, LOM, RFA, RFB Input Power (Note 17) ......+20dBm Output Short Circuit Duration (Notes 14, 17)... Indefinite Maximum Junction Temperature (TJMax) ............. $150^{\circ} \mathrm{C}$ Case Operating Temperature Range ( $\mathrm{T}_{\mathrm{C}}$ ) $-40^{\circ} \mathrm{C}$ to $105^{\circ} \mathrm{C}$ Storage Temperature Range $\qquad$ $-65^{\circ} \mathrm{C}$ to $150^{\circ} \mathrm{C}$

## PIn CONFIGURATION



## ORDER INFORMATION

| LEAD FREE FINISH | TAPE AND REEL | PART MARKING | PACKAGE DESCRIPTION | TEMPERATURE RANGE |
| :--- | :--- | :--- | :--- | :--- |
| LTC5586IUH\#PBF | LTC5586IUH\#TRPBF | 5586 | $32-$ Lead $(5 \mathrm{~mm} \times 5 \mathrm{~mm})$ Plastic QFN | $-40^{\circ} \mathrm{C}$ to $105^{\circ} \mathrm{C}$ |

[^0]Tape and reel specifications. Some packages are available in 500 unit reels through designated sales channels with \#TRMPBF suffix.

ELECTRICAL CHARACTERISTICS
$\mathrm{T}_{\mathrm{C}}=25^{\circ} \mathrm{C}, \mathrm{V}_{\mathrm{CC}}=\mathrm{V}_{\mathrm{CCN}}=5 \mathrm{~V}, 0 \mathrm{VDD}=\mathrm{CSB}=\mathrm{RFSW}=3.3 \mathrm{~V}, \mathrm{SDI}=\mathrm{SCK}=0 \mathrm{~V}$, $\mathrm{VCM}=0.9 \mathrm{~V}, \mathrm{P}_{\mathrm{IF}}=1.5 \mathrm{dBm}\left(-1.5 \mathrm{dBm} /\right.$ tone for 2 -tone tests), $\mathrm{P}_{\mathrm{L} 0}=6 \mathrm{dBm}$, all registers at default values unless otherwise noted.
(Notes 2, 3, 6, 9, 19, 22)

| SYMBOL | PARAMETER | CONDITIONS | MIN TYP | MAX | UNITS |
| :---: | :---: | :---: | :---: | :---: | :---: |
| $\mathrm{frfa}_{\text {(RANGE) }}$ | RF Input Frequency Range | (Note 12) | 0.3 to 6.0 |  | GHz |
| flo(RANGE) | LO Input Frequency Range | (Note 12) | 0.3 to 6.0 |  | GHz |
| RL RF | RF Input Return Loss | $\begin{aligned} & \mathrm{f}_{\mathrm{RF}}=300 \mathrm{MHz} \text { to } 500 \mathrm{MHz} \text { (Note } 5 \text { ) } \\ & \mathrm{f}_{\mathrm{RF}}=500 \mathrm{MHz} \text { to } 6.0 \mathrm{GHz} \end{aligned}$ | $\begin{aligned} & >10 \\ & >10 \end{aligned}$ |  | dB dB |
| RL ${ }_{\text {L0 }}$ | LO Input Return Loss | $\mathrm{f}_{\mathrm{L} 0}=300 \mathrm{MHz}$ to 6.0 GHz | >10 |  | dB |
| Plo(RANGE) | LO Input Power Range | (Note 12) | -6 to 12 |  | dBm |
| $\mathrm{GP}_{\text {(MAX) }}$ | Maximum Power Conversion Gain ATT $=0 \times 00, \mathrm{AMPG}=0 \times 06$, $R_{\text {LOAD }}=100 \Omega$ Differential (Note 8) | $\begin{aligned} & f_{R F}=400 \mathrm{MHz} \\ & f_{R F}=900 \mathrm{MHz} \\ & f_{R F}=1900 \mathrm{MHz} \\ & f_{R F}=2600 \mathrm{MHz} \\ & f_{R F}=3500 \mathrm{MHz} \\ & f_{R F}=5800 \mathrm{MHz} \end{aligned}$ | $\begin{aligned} & 7.4 \\ & 9.2 \\ & 7.7 \\ & 7.1 \\ & 4.3 \\ & 0.7 \\ & \hline \end{aligned}$ |  | dB $d B$ $d B$ $d B$ $d B$ $d B$ |
| $\mathrm{G}_{\text {P(MIN) }}$ | Power Conversion Gain at Maximum Attenuation. ATT $=0 \times 1 \mathrm{~F}, \mathrm{AMPG}=0 \times 06$, $R_{\text {LOAD }}=100 \Omega$, Differential (Note 8) | $\begin{aligned} & f_{R F}=400 \mathrm{MHz} \\ & f_{R F}=900 \mathrm{MHz} \\ & f_{R F}=1900 \mathrm{MHz} \\ & f_{R F}=2600 \mathrm{MHz} \\ & f_{R F}=3500 \mathrm{MHz} \\ & f_{R F}=5800 \mathrm{MHz} \end{aligned}$ | $\begin{aligned} & -23.3 \\ & -21.3 \\ & -21.8 \\ & -23.5 \\ & -24.0 \\ & -23.9 \end{aligned}$ |  | dB $d B$ $d B$ $d B$ $d B$ $d B$ |
|  | Attenuation Step Size |  | 1.0 |  | dB |
|  | Attenuation Step Accuracy |  | 0.2 |  | dB |
|  | RFA, RFB Gain Error |  | 0.05 |  | dB |
|  | RFA, RFB Switching Time |  | 100 |  | ns |
| $\overline{A B_{\mid S O}}$ | RFA, RFB Isolation | $\begin{aligned} & f_{R F}=400 \mathrm{MHz} \\ & f_{\mathrm{RF}}=900 \mathrm{MHz} \\ & f_{\mathrm{RF}}=1900 \mathrm{MHz} \\ & f_{\mathrm{RF}}=2600 \mathrm{MHz} \\ & f_{\mathrm{RF}}=3500 \mathrm{MHz} \\ & f_{\mathrm{RF}}=5800 \mathrm{MHz} \end{aligned}$ | $\begin{aligned} & 49 \\ & 48 \\ & 40 \\ & 42 \\ & 38 \\ & 25 \end{aligned}$ |  | dB $d B$ $d B$ $d B$ $d B$ $d B$ |
| NF | Noise Figure, Double Side Band (Note 4) | $\begin{aligned} & f_{R F}=400 \mathrm{MHz} \\ & f_{R F}=900 \mathrm{MHz} \\ & f_{R F}=1900 \mathrm{MHz} \\ & f_{R F}=2600 \mathrm{MHz} \\ & f_{R F}=3500 \mathrm{MHz} \\ & f_{R F}=5800 \mathrm{MHz} \end{aligned}$ | $\begin{aligned} & 19.0 \\ & 17.8 \\ & 19.5 \\ & 21.1 \\ & 23.2 \\ & 31.0 \end{aligned}$ |  | dB $d B$ $d B$ $d B$ $d B$ $d B$ |
| $\overline{N F}$ BLOCKING | Noise Figure Under Blocking Conditions Double Side Band, PIF, BLOCKER $=1.5 \mathrm{dBm}$ (Note 7) | $\begin{aligned} & f_{R F}=400 \mathrm{MHz} \\ & f_{R F}=900 \mathrm{MHz} \\ & f_{R F}=1900 \mathrm{MHz} \\ & f_{R F}=2600 \mathrm{MHz} \\ & f_{R F}=3500 \mathrm{MHz} \\ & f_{R F}=5800 \mathrm{MHz} \end{aligned}$ | $\begin{aligned} & 19.7 \\ & 18.9 \\ & 20.8 \\ & 22.5 \\ & 24.8 \\ & 30.2 \end{aligned}$ |  | $d B$ $d B$ $d B$ $d B$ $d B$ $d B$ |
| OIP3 | Output 3rd Order Intercept Unadjusted/Adjusted | $\begin{aligned} & \mathrm{f}_{\mathrm{fF}}=400 \mathrm{MHz} \\ & \mathrm{f}_{\mathrm{fF}}=900 \mathrm{MHz} \\ & f_{\mathrm{fF}}=1900 \mathrm{MHz} \\ & \mathrm{f}_{\mathrm{RF}}=2600 \mathrm{MHz} \\ & \mathrm{f}_{\mathrm{RF}}=3500 \mathrm{MHz} \\ & \mathrm{f}_{\mathrm{RF}}=5800 \mathrm{MHz} \end{aligned}$ | 41/44 42/43 40/42 38/40 35/36 32/33 |  |  |
| OIP2 | Output 2nd Order Intercept Unadjusted/Adjusted | $\begin{aligned} & f_{R F}=400 \mathrm{MHz} \\ & f_{R F}=900 \mathrm{MHz} \\ & f_{R F}=1900 \mathrm{MHz} \\ & f_{R F}=2600 \mathrm{MHz} \\ & f_{R F}=3500 \mathrm{MHz} \\ & f_{R F}=5800 \mathrm{MHz} \end{aligned}$ | $\begin{aligned} & 75 / 80 \\ & 75 / 80 \\ & 74 / 80 \\ & 65 / 80 \\ & 60 / 70 \\ & 49 / 56 \end{aligned}$ |  | dBm <br> dBm <br> dBm <br> dBm <br> dBm <br> dBm |
|  |  |  |  |  | Rev B |

## LTC5586

ELECTRICAL CHARACTERISTICS $\mathrm{T}_{\mathrm{C}}=25^{\circ} \mathrm{C}, \mathrm{V}_{C C}=\mathrm{V}_{C C N}=5 \mathrm{~V}, \mathrm{OVDD}=C S B=R F S W=3.3 \mathrm{~V}, S D I=S C K=0 \mathrm{~V}$, $\mathrm{VCM}=0.9 \mathrm{~V}, \mathrm{P}_{\mathrm{IF}}=1.5 \mathrm{dBm}\left(-1.5 \mathrm{dBm} /\right.$ tone for 2 -tone tests), $\mathrm{P}_{\mathrm{L} 0}=6 \mathrm{dBm}$, all registers at default values unless otherwise noted.
(Notes 2, 3, 6, 9, 19, 22)


ELECTRICAL CHARACTERISTICS
$\mathrm{T}_{\mathrm{C}}=25^{\circ} \mathrm{C}, \mathrm{V}_{\mathrm{CC}}=\mathrm{V}_{\mathrm{CCN}}=5 \mathrm{~V}, \mathrm{OVDD}=\mathrm{CSB}=\mathrm{RFSW}=3.3 \mathrm{~V}, \mathrm{SDI}=\mathrm{SCK}=0 \mathrm{~V}$, $\mathrm{VCM}=0.9 \mathrm{~V}, \mathrm{P}_{\mathrm{IF}}=1.5 \mathrm{dBm}\left(-1.5 \mathrm{dBm} /\right.$ tone for 2 -tone tests), $\mathrm{P}_{\mathrm{L} 0}=6 \mathrm{dBm}$, all registers at default values unless otherwise noted.
(Notes 2, 3, 6, 9, 19, 22)

| SYMBOL | PARAMETER | CONDITIONS | MIN | TYP | MAX | UNITS |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| $\Delta \phi_{\text {(STEP })}$ | I/Q Phase Mismatch Adjustment Step Size |  |  | 0.05 |  | Deg |
| IRR | Image Rejection Ratio Unadjusted/Adjusted (Note 10) | $\begin{aligned} & \hline f_{R F}=400 \mathrm{MHz} \\ & f_{R F}=700 \mathrm{MHz} \\ & f_{R F}=1900 \mathrm{MHz} \\ & f_{R F}=2600 \mathrm{MHz} \\ & f_{R F}=3500 \mathrm{MHz} \\ & f_{R F}=5800 \mathrm{MHz} \end{aligned}$ |  | $\begin{aligned} & \hline 51 / 68 \\ & 44 / 70 \\ & 45 / 68 \\ & 39 / 69 \\ & 33 / 70 \\ & 39 / 70 \end{aligned}$ |  | dB $d B$ $d B$ $d B$ $d B$ $d B$ |
| LR LEAK | LO to RF Leakage | $\begin{aligned} & \mathrm{f}_{\mathrm{LO}}=400 \mathrm{MHz} \\ & \mathrm{f}_{\mathrm{LO}}=900 \mathrm{MHz} \\ & \mathrm{f}_{\mathrm{LO}}=1900 \mathrm{MHz} \\ & \mathrm{f}_{\mathrm{LO}}=2600 \mathrm{MHz} \\ & \mathrm{f}_{\mathrm{LO}}=3500 \mathrm{MHz} \\ & \mathrm{f}_{\mathrm{LO}}=5800 \mathrm{MHz} \end{aligned}$ |  | $\begin{aligned} & -67 \\ & -63 \\ & -56 \\ & -55 \\ & -45 \\ & -47 \end{aligned}$ |  |  |
| RLISO | RF to LO Isolation | $\begin{aligned} & f_{R F}=400 \mathrm{MHz} \\ & f_{R F}=900 \mathrm{MHz} \\ & f_{R F}=1900 \mathrm{MHz} \\ & f_{R F}=2600 \mathrm{MHz} \\ & f_{R F}=3500 \mathrm{MHz} \\ & f_{R F}=5800 \mathrm{MHz} \end{aligned}$ |  | $\begin{aligned} & 59 \\ & 65 \\ & 66 \\ & 62 \\ & 57 \\ & 52 \end{aligned}$ |  | dB $d B$ $d B$ $d B$ $d B$ $d B$ |
| $\mathrm{Rl}_{\text {ISO }}$ | RF to IF Isolation (Note 16) | $\begin{aligned} & f_{R F}=400 \mathrm{MHz} \\ & f_{R F}=900 \mathrm{MHz} \\ & f_{R F}=1900 \mathrm{MHz} \\ & f_{R F}=2600 \mathrm{MHz} \\ & f_{R F}=3500 \mathrm{MHz} \\ & f_{R F}=5800 \mathrm{MHz} \end{aligned}$ |  | $\begin{aligned} & 70 \\ & 65 \\ & 50 \\ & 53 \\ & 48 \\ & 47 \end{aligned}$ |  | dB $d B$ $d B$ $d B$ $d B$ $d B$ |
| $\mathrm{L}_{\text {LEAK }}$ | LO to IF Leakage (Note 16) | $\begin{aligned} & \mathrm{f}_{\mathrm{LO}}=400 \mathrm{MHz} \\ & \mathrm{f}_{\mathrm{LO}}=900 \mathrm{MHz} \\ & \mathrm{f}_{\mathrm{LO}}=1900 \mathrm{MHz} \\ & \mathrm{f}_{\mathrm{LO}}=2600 \mathrm{MHz} \\ & \mathrm{f}_{\mathrm{LO}}=3500 \mathrm{MHz} \\ & \mathrm{f}_{\mathrm{LO}}=5800 \mathrm{MHz} \end{aligned}$ |  | $\begin{aligned} & -37 \\ & -36 \\ & -34 \\ & -33 \\ & -42 \\ & -36 \end{aligned}$ |  |  |

Power Supply and Other Parameters

| $\mathrm{V}_{\text {CC }}, \mathrm{V}_{\text {CCN }}$ | Supply Voltage |  | 4.75 5.0 5.25 | V |
| :---: | :---: | :---: | :---: | :---: |
| ICC | Supply Current |  | $430 \quad 440 \quad 470$ | mA |
| IvCCN | Supply Current to VCCN Pin |  | 700 | $\mu \mathrm{A}$ |
| $\mathrm{OV}_{\text {DD }}$ | Digital I/O Supply Voltage |  | 1.2 to 3.3 | V |
| $\mathrm{V}_{\text {DH }}$ | RFSW Input High Voltage (On) |  | $0.7 \bullet 0 V_{D D}$ | V |
| $\mathrm{V}_{\text {DL }}$ | RFSW Input Low Voltage (Off) |  | $0.3 \cdot \mathrm{~V}_{\mathrm{DD}}$ | V |
| $\underline{\text { IRFSW }}$ | RFSW Pin Input Current | RFSW $=3.3 \mathrm{~V}$ | 1 | $\mu \mathrm{A}$ |
| $\mathrm{V}_{\text {TEMP }}$ | TEMP Diode Bias Voltage | $\mathrm{I}_{\text {TEMP }}=100 \mu \mathrm{~A}$ into TEMP pin, $\mathrm{T}_{\mathrm{J}}=25^{\circ} \mathrm{C}$ | 0.774 | V |
|  | TEMP Diode Temperature Slope | $I_{\text {TEMP }}=100 \mu \mathrm{~A}$ into TEMP pin | -1.52 | $\mathrm{mV} /{ }^{\circ} \mathrm{C}$ |
| $\underline{\mathrm{Z}_{\text {MIX(OUT) }}}$ | Mixer Output Impedance | Differential | 100\||0.6 | $\Omega \\| \mathrm{pF}$ |
| $\mathrm{V}_{\text {MIX(OUT) }}$ | Mixer Output DC Voltage | Common-Mode | 3.6 | V |
| Z ${ }_{\text {AMP(IN) }}$ | Amplifier Input Impedance | Differential | 200\||0.2 | $\Omega \\| \mathrm{pF}$ |
| $\mathrm{V}_{\text {AMP(IN) }}$ | Amplifier DC Input Voltage | Common-Mode | 3.0 to 4.0 | V |
| $\underline{\mathrm{Z}_{\text {AMP(0UT) }}}$ | Amplifier Output Impedance | Differential | $4\|\mid 0.5$ | $\mathrm{k} \Omega \\| \mathrm{pF}$ |
| $\mathrm{I}_{\text {AMP(SC) }}$ | Amplifier DC Output Short Circuit Current | IFIP $=$ IFIM $=$ IFQP $=\mathrm{IFQM}=0 \mathrm{~V}$ | 100 | mA |
| $\mathrm{V}_{\text {CM (RANGE) }}$ | VCM Pin Voltage Range (Notes 11, 12) |  | 0.5 to 2.0 | V |

ELECTRICAL CHARACTERISTICS $\mathrm{T}_{\mathrm{C}}=25^{\circ} \mathrm{C}, \mathrm{V}_{C C}=\mathrm{V}_{C C N}=5 \mathrm{~V}, 0 \mathrm{VDD}=\mathrm{CSB}=\mathrm{RFSW}=3.3 \mathrm{~V}, \mathrm{SDI}=\mathrm{SCK}=0 \mathrm{~V}$, $\mathrm{VCM}=0.9 \mathrm{~V}, \mathrm{P}_{\mathrm{IF}}=1.5 \mathrm{dBm}\left(-1.5 \mathrm{dBm} /\right.$ tone for 2 -tone tests), $\mathrm{P}_{\mathrm{L} 0}=6 \mathrm{dBm}$, all registers at default values unless otherwise noted. (Notes 2, 3, 6, 9, 19, 22)

| SYMBOL | PARAMETER | CONDITIONS | MIN | TYP | MAX |
| :--- | :--- | :--- | ---: | ---: | ---: |
| UNITS $^{\text {BW }}$ | IF Output Bandwidth | $-1 d B$ Corner Frequency (Note 20) | 1.0 | GHz |  |

Serial Interface Pins

| $\mathrm{V}_{\text {IH }}$ | High Level Input Voltage | CSB, SDI, SCK | $0.7 \cdot 0 V_{\text {DD }}$ | V |
| :---: | :---: | :---: | :---: | :---: |
| $\mathrm{V}_{\text {IL }}$ | Low Level Input Voltage | CSB, SDI, SCK | $0.3 \cdot \mathrm{~V}_{\mathrm{DD}}$ | V |
| $\mathrm{V}_{\text {IHYS }}$ | Input Hysteresis Voltage | CSB, SDI, SCK | 250 | mV |
| $\underline{\text { IN(SER) }}$ | Input Current | CSB, SDI, SCK (Note 17) | 30 | $\mu \mathrm{A}$ |
| $\mathrm{V}_{\text {OH }}$ | High Level Output Voltage | SDO, 10mA Current Sink | $0.7 \bullet 0 \mathrm{~V}_{\mathrm{DD}}$ | V |
| $\mathrm{V}_{\text {OL }}$ | Low Level Output Voltage | SDO, 10mA Current Source | $0.3 \bullet$ OV ${ }_{\text {DD }}$ | V |

## Serial Interface Timing

| $t_{\text {CKH }}$ | SCK High Time |  | 25 | ns |
| :--- | :--- | :--- | :--- | :---: |
| $t_{\text {CKL }}$ | SCK Low Time |  | 25 | ns |
| $t_{\text {CSS }}$ | CSB Setup Time |  | 10 | ns |
| $t_{\text {CSH }}$ | CSB High Time |  | 10 | ns |
| $t_{D S}$ | SDI to SCK Setup Time |  | 6 | ns |
| $t_{\text {DH }}$ | SDI to SCK Hold Time |  | 6 | ns |
| $t_{\text {DO }}$ | SCK to SDO Time | To $V_{I H} / V_{\text {IL }} / H i-Z$ with 30pF Load | ns |  |

Note 1: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. Exposure to any Absolute Maximum Rating condition for extended periods may affect device reliability and lifetime. The voltage on all pins should not exceed $V_{C C}+0.3 V$ or be less than -0.3 V , otherwise damage to the ESD diodes may occur.
Note 2: Tests are performed with the test circuit of Figure 1.
Note 3: The LTC5586 is guaranteed to be functional over the $-40^{\circ} \mathrm{C}$ to $105^{\circ} \mathrm{C}$ case temperature operating range.
Note 4: DSB noise figure is measured at the baseband frequency of 15 MHz with a small-signal noise source without any filtering on the RF input and no other RF signal applied.
Note 5: A 4.7pF shunt capacitor is used on the RF inputs for 300 MHz to 500 MHz . 0.3 pF is used for 500 MHz to 6 GHz .
Note 6: The differential amplifier outputs (IFIP, IFIM and IFQP, IFQM) are combined using a $180^{\circ}$ combiner.
Note 7: Noise figure under blocking conditions (NFBlocking) is measured at an output frequency of 60 MHz with RF input signal at $\mathrm{f}_{\mathrm{L} O}+1 \mathrm{MHz}$. Both RF and LO input signals are appropriately filtered, as well as the baseband output.
Note 8: Power conversion gain is defined from the RFA (or RFB) input to the I or $Q$ output. Power conversion gain is measured with a $100 \Omega$ differential load impedance on the I and $Q$ outputs. Any losses due to IF combiner and spectrum analyzer termination have been de-embedded.

Note 9: Input $P_{\text {RF }}$ adjusted so that $P_{\text {IF }}=-1.5 d B m / t o n e$ at the amplifier output. RF tone spacing set at 4 MHz with high-side $\mathrm{LO}, \mathrm{f}_{\mathrm{LO}}=\mathrm{f}_{\mathrm{RF}}+30 \mathrm{MHz}$.
Note 10: Image rejection is measured at $\mathrm{f}_{\mathrm{IF}}=12 \mathrm{MHz}$ and calculated from the measured gain error and phase error.
Note 11: If the VCM pin is left floating, it will self bias to a nominal 0.9 V .
Note 12: This is the recommended operating range, operation outside the listed range is possible with degraded performance to some parameters.
Note 13: DC offset measured differentially between IFIP and IFIM and between IFQP and IFQM. The reported value is the mean of the absolute values of the characterization data distribution.
Note 14: IF outputs shorted to ground.
Note 15: IF tone spacing set at 1 MHz .
Note 16: Worst case leakage or isolation measured to each IF single-ended port.
Note 17: Guaranteed by design characterization, not tested in production.
Note 18: The voltage on the OVDD pin must never exceed $\mathrm{V}_{C C}+0.3 \mathrm{~V}$, otherwise damage to the ESD diodes may occur.
Note 19: Refer to Appendix for register definition and default values.
Note 20: Mixer outputs directly connected to amplifier inputs. Bandwidth measured on single amplifier output, I or $Q$.
Note 21: $\mathrm{V}_{\mathrm{CC}}$ should be ramped up slower than $5 \mathrm{~V} / \mathrm{ms}$ to prevent damage.
Note 22: $\mathrm{P}_{\text {IF }}$ measured at amplifier differential outputs.

TYPICAL PERFORMANCE CHARACTERISTICS $V_{C C}=V_{C C N}=5 \mathrm{~V}, \mathrm{~T}_{\mathrm{C}}=25^{\circ} \mathrm{C}, \mathrm{P}_{\mathrm{L} O}=6 \mathrm{dBm}, \mathrm{HSLO}, \mathrm{RF}$ tone spacing $=4 \mathrm{MHz}, \mathrm{f}_{\mathrm{IF}}=30 \mathrm{MHz}, \mathrm{P}_{\mathrm{IF}}=-1.5 \mathrm{dBm}$ per tone, and register defaults. DC Blocks, $50 \Omega$ terminations, and MACOM H9 $180^{\circ}$ combiner at amplifier outputs de-embedded from measurement unless otherwise noted. Test circuit shown in Figure 1 with 500 MHz interstage filter.


Noise Figure and Conversion Gain vs LO Power


Gain vs IF Frequency for Various


TEMP Diode Voltage vs Junction Temperature ( $\mathrm{T}_{\mathrm{J}}$ )



Gain vs IF Frequency for Various Fixed LO Frequencies



Noise Figure and Conversion Gain vs Temperature ( $\mathrm{T}_{\mathrm{C}}$ )


586 G04

Gain vs AMPG Register Value


Noise Figure vs ATT Setting

TYPICAL PGßFORMAOCE CHARACTERISTICS $V_{C c}=V_{C C N}=5 V, T_{C}=25^{\circ} C, P_{L 0}=6 d B m$, HSLO, RF tone spacing $=4 \mathrm{MHz}, \mathrm{f}_{\mathrm{IF}}=30 \mathrm{MHz}, \mathrm{P}_{\mathrm{IF}}=-1.5 \mathrm{dBm}$ per tone, and register defaults. DC Blocks, $50 \Omega$ terminations, and MACOM H9 180 combiner at amplifier outputs de-embedded from measurement unless otherwise noted. Test circuit shown in Figure 1 with 500 MHz interstage filter.







## Optimized OIP3 vs Temperature ( $\mathrm{T}_{\mathrm{C}}$ )




TYPICAL PERFORMAOCE CHARACTERISTICS $V_{C C}=V_{C C N}=5 \mathrm{~V}, \mathrm{~T}_{\mathrm{C}}=25^{\circ} \mathrm{C}, \mathrm{P}_{\mathrm{L} O}=6 \mathrm{dBm}, \mathrm{HSLO}, \mathrm{RF}$ tone spacing $=4 \mathrm{MHz}, \mathrm{f}_{\mathrm{IF}}=30 \mathrm{MHz}, \mathrm{P}_{\mathrm{IF}}=-1.5 \mathrm{dBm}$ per tone, and register defaults. DC Blocks, $50 \Omega$ terminations, and MACOM H9 $180^{\circ}$ combiner at amplifier outputs de-embedded from measurement unless otherwise noted. Test circuit shown in Figure 1 with 500 MHz interstage filter.









OIP2 vs Temperature ( $\mathrm{T}_{\mathrm{c}}$ ) and Register Value, I-Channel


TYPICAL PGßFORMAOCE CHARACTERISTICS $V_{C C}=V_{c c N}=5 \mathrm{~V}, \mathrm{~T}_{\mathrm{C}}=25^{\circ} \mathrm{C}, \mathrm{P}_{\mathrm{LO}}=6 \mathrm{dBm}, \mathrm{HSLO}$, RF tone spacing $=4 \mathrm{MHz}, \mathrm{f}_{\mathrm{IF}}=30 \mathrm{MHz}, \mathrm{P}_{\mathrm{IF}}=-1.5 \mathrm{dBm}$ per tone, and register defaults. DC Blocks, $50 \Omega$ terminations, and MACOM H9 180 ${ }^{\circ}$ combiner at amplifier outputs de-embedded from measurement unless otherwise noted. Test circuit shown in Figure 1 with 500 MHz interstage filter.


Optimized HD2
vs Temperature ( $\mathrm{T}_{\mathrm{C}}$ )


HD3 vs Temperature ( $\mathrm{T}_{\mathrm{C}}$ )


HD2 vs Temperature ( $\mathrm{T}_{\mathrm{C}}$ )


HD2 vs Temperature ( $\mathrm{T}_{\mathrm{C}}$ ) and Register Value, I-Channel


## HD3 vs LO Power



HD2 vs LO Power


HD2 vs Temperature ( $\mathrm{T}_{\mathrm{C}}$ ) and Register Value, Q-Channel


Optimized HD3 vs Temperature ( $\mathrm{T}_{\mathrm{C}}$ )


TYPICAL PERFORMANCE CHARACTERISTICS $v_{C C}=V_{C C N}=5 \mathrm{~V}, \mathrm{~T}_{\mathrm{C}}=25^{\circ} \mathrm{C}, \mathrm{P}_{\mathrm{L} 0}=6 \mathrm{dBm}, \mathrm{HSLO}, \mathrm{RF}$ tone spacing $=4 \mathrm{MHz}, \mathrm{f}_{\mathrm{IF}}=30 \mathrm{MHz}, \mathrm{P}_{\mathrm{IF}}=-1.5 \mathrm{dBm}$ per tone, and register defaults. DC Blocks, $50 \Omega$ terminations, and MACOM H9 $180^{\circ}$ combiner at amplifier outputs de-embedded from measurement unless otherwise noted. Test circuit shown in Figure 1 with 500MHz interstage filter.


Optimized Image Rejection vs Temperature ( $\mathrm{T}_{\mathrm{C}}$ )



HD3 vs Temperature ( $\mathrm{T}_{\mathrm{C}}$ ) and Register Value, Q-Channel


Gain Error vs Temperature ( $\mathrm{T}_{\mathrm{C}}$ ) and GERR Register Value


## DC Offset vs LO Power



Image Rejection vs Temperature ( $\mathrm{T}_{\mathrm{C}}$ )


Phase Error vs Temperature ( $\mathrm{T}_{\mathrm{C}}$ ) and PHA Register Value


Optimized DC Offset vs Temperature ( $\mathrm{T}_{\mathrm{C}}$ )


TYPICAL PERFORMAOCE CHARACTGRISTICS $V_{C C}=V_{C C N}=5 \mathrm{~V}, \mathrm{~T}_{\mathrm{C}}=25^{\circ} \mathrm{C}, \mathrm{P}_{\mathrm{L} O}=6 d \mathrm{Bm}, \mathrm{HSLO}, \mathrm{RF}$ tone spacing $=4 \mathrm{MHz}, \mathrm{f}_{\mathrm{IF}}=30 \mathrm{MHz}, \mathrm{P}_{\mathrm{IF}}=-1.5 \mathrm{dBm}$ per tone, and register defaults. DC Blocks, $50 \Omega$ terminations, and MACOM H9 180 combiner at amplifier outputs de-embedded from measurement unless otherwise noted. Test circuit shown in Figure 1 with 500 MHz interstage filter.



TYPICAL PERFORMAOCE CHARACTERISTICS $V_{C C}=V_{C C N}=5 \mathrm{~V}, \mathrm{~T}_{\mathrm{C}}=25^{\circ} \mathrm{C}, \mathrm{P}_{\mathrm{L} O}=6 \mathrm{dBm}, \mathrm{HSLO}, \mathrm{RF}$ tone spacing $=4 \mathrm{MHz}, \mathrm{f}_{\mathrm{IF}}=30 \mathrm{MHz}, \mathrm{P}_{\mathrm{IF}}=-1.5 \mathrm{dBm}$ per tone, and register defaults. DC Blocks, $50 \Omega$ terminations, and MACOM H9 180 combiner at amplifier outputs de-embedded from measurement unless otherwise noted. Test circuit shown in Figure 1 with 500 MHz interstage filter.


## Image Rejection Distribution vs Temperature ( $\mathrm{T}_{\mathrm{C}}$ )



Optimized Image Rejection vs IF Frequency


## PIn fUnCTIOnS

RFA (Pin 2): $50 \Omega$ switched RF input. The pin should be DC-blocked with coupling capacitor; 1000pF is recommended.

TEMP (Pin 3): Temperature monitoring diode. The diode to ground at this pin can be used to measure the die temperature. A forward bias current of $100 \mu \mathrm{~A}$ can be used into this pin and the forward voltage drop can be measured as a function of die temperature.

RFSW (Pin 4): RF channel select. The state of the RF switch is the logical AND of the RFSW pin and the RFSW register value. (See Appendix). This pin should not be left floating. Either tie high or low.

VCCN (Pin 5): Positive Supply Pin. This pin must be tied to the VCC pin.
VCM (Pin 6): IF amplifier common-mode output voltage adjust. Source resistance should be $1 \mathrm{k} \Omega$ or lower. If this pin is left unconnected, it will internally self-bias to 0.9 V .
RFB (Pin 7): $50 \Omega$ switched RF input. The pin should be DC-blocked with coupling capacitor; 1000pF is recommended.

MQP, MQM, MIM, MIP (Pins 9, 10, 31, 32): Mixer differential output pins. When connected to the amplifier input pins, the $D C$ bias point is $V_{C C}-1.4 \mathrm{~V}$ for each pin. A low-pass filter is typically used between the MQM(P) or MIM(P) pins and the AQM $(P)$ or AIM(P) pins to suppress the high frequency mixing products. See the Applications section for more information.
DNC (Pins 11, 14, 27, 30): DO NOT CONNECT. No connection should be made to these pins.

AQM, AQP, AIP, AIM (Pins 12, 13, 28, 29): Amplifier differential input pins. When connected to the mixer output pins, the $D C$ bias point is $V_{C C}-1.4 \mathrm{~V}$ for each pin. A low-pass filter is typically used between the AQM(P) or AIM(P) pins and the MQM(P) or MIM(P) pins to suppress the high frequency mixing products. See the Applications section for more information.

IFQM, IFQP, IFIP, IFIM (Pins 15, 16, 25, 26): IF amplifier output pins. The current used by the output amplifiers is set by a resistance of $25 \Omega$ to $200 \Omega$ from each pin to ground and the VCM control voltage.

CSB (Pin 17): Chip Select Bar. When CSB is low, the serial interface is enabled. It can be driven with 1.2 V to 3.3 V logic levels.
VCC (Pin 18): Positive supply pin. This pin should be bypassed with a 1000 pF and $4.7 \mu \mathrm{~F}$ capacitor to ground.
LOP, LOM (Pins 19, 20): LO inputs. External matching is not needed. Can be driven $50 \Omega$ single-ended or $100 \Omega$ differentially. The LO pins should be DC-blocked with coupling capacitor; 1000pF is recommended. When driven single-ended, the unused pin should be terminated with $50 \Omega$ in series with the DC-blocking capacitor.
SDO (Pin 21): Serial Data Output. This output can accommodate logic levels from 1.2 V to 3.3 V . During read-mode, data is read out MSB first.

SDI (Pins 22): Serial Data Input. Data is clocked MSB first into the mode-control registers on the rising edge of SCK. SDI can be driven with 1.2 V to 3.3 V logic levels.

SCK (Pin 23): Serial Clock Input. SDI can be driven with 1.2V to 3.3V logic levels.

OVDD (Pin 24): Positive digital interface supply pin. This pin sets the logic levels for the digital interface. 1.2 V to 3.3 V can be used. This pin should be bypassed with a $1 \mu \mathrm{~F}$ capacitor to ground. The VCC supply must be applied before the OVDD supply to prevent damage to the ESD diodes.

GND (Pins 1, 8, Exposed Pad Pin 33): Ground. These pins must be soldered to the circuit board RF ground plane. The backside exposed pad ground connection should have a low-inductance connection and good thermal contact to the printed circuit board ground plane using many through-hole vias. See layout information.

## BLOCK DIAGRAM



## LTC5586

timing diagrams


SPI Port Timing (Write Mode)


## TEST CIRCUIT



| REF DES | VALUE | SIZE | VENDOR | REF DES | VALUE | SIZE | VENDOR |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| C1, C3, C6, C8, C42 | 1000 pF | 0402 | Murata | L1-L4 | 22 nH | 0805 | Coilcraft |
| C2, C4, C5, C7 | 0.3 pF | 0402 | Murata | R1, R3, R4, R11, R12 | $49.9 \Omega$ | 0402 |  |
| C9-C16 | 3.0 pF | 0201 | Murata | R5, R13 | $0 \Omega$ | 0402 |  |
| C40 | $1 \mu \mathrm{~F}$ | 0603 | Murata | R20 | $40.2 \mathrm{k} \Omega$ | 0402 |  |
| C43 | 4.7 F 2 | 0805 | Murata |  |  |  |  |

Figure 1. Test Circuit Schematic

## LTC5586

## TEST CIRCUIT



Figure 2. Component Side of Evaluation Board


Figure 3. Bottom Side of Evaluation Board

## APPLICATIONS INFORMATION

The LTC5586 is an IQ demodulator designed for high dynamic range receiver applications. It consists of RF switches, a step attenuator, I/Q mixers, quadrature LO amplifiers, IF amplifiers, and correction circuitry for DC offset, image rejection, and non-linearity.

## Operation

As shown in the Block Diagram for the LTC5586, the RF inputs, RFA and RFB, are selected by an internal switch. The RF signal is then converted to a differential signal by the on-chip balun transformer covering the 300MHz to 6 GHz band. A differential 0 to 31 dB step attenuator then scales the RF input level to the I and Q channel mixers.

The LO inputs are impedance matched using a programmable network, and then accurately shifted in phase by $90^{\circ}$ by an internal precision phase shifter. This phase shifter maintains the accurate quadrature relation over the full LO input range from 300 MHz to 6 GHz . In addition, the phase shifter allows fine tuning of the phase difference between the I- and Q-channel LO with a resolution of around 0.05 degrees to compensate for any phase mismatch between the mixers and phase mismatch introduced into the IF path by any filter component mismatch.

The differential mixer IF output signals are filtered off-chip to remove the $f_{R F}+f_{L O}$ signal and other high frequency mixing products before being applied to the on-chip IF amplifiers. The IF amplifiers have adjustable gain and common-mode output voltage to allow for direct interfacing with A/D converters. The gain balance between both IF output channels of the LTC5586 can be fine tuned with
a resolution of about 0.016 dB in order to compensate for gain mismatches in the IF signal path, either caused internally by the device or by external amplifiers and filters. The DC offset in both IF channels can be adjusted in order to minimize the accumulated $D C$ offset at the $A / D$ converter input.

The RF switch state, attenuation, IF gain, gain error and phase error adjust, DC offset adjust, and non-linearity adjust registers are digitally controlled through a 4-wire SPI interface. The register map is detailed in the Appendix.

## RF Input Ports

Figure 4 shows a simplified schematic of the demodulator's RF inputs (the RFA input is identical to RFB input) which consist of an RF switch, balun transformer, and step-attenuator. External DC voltage should not be applied to the RF input pins. DC current flowing into the pins may cause damage to the chip. Series DC blocking capacitors should be used to couple the RF input pins to the RF signal sources. The RF switch can be selected by the RFSW pin, and by the RFSW register 0x17 bit[0]. The RFA input is selected when the logical AND of the value of RFSW in register 0x17 and the logic level of the RFSW pin is 1 (see digital input pins section and register map). The switch state is detailed in Table 1.

Table 1. RF Switch State vs Logic Levels

| RFSW <br> Register | RFSW Pin |  |
| :---: | :---: | :---: |
|  | $\mathbf{0}$ | $\mathbf{1}$ |
| 0 | RFB | RFB |
| 1 | RFB | RFA |



Figure 4. Simplified Schematic of the RF Input with External Matching Components

## APPLICATIONS InFORMATION

As shown in Figure 5, the RF input ports are well matched with return loss greater than 10 dB over the frequency range of 500 MHz to 6 GHz with a 0.3 pF capacitor on C2. The RF pins can be externally matched over the 300 MHz to 500 MHz frequency range by changing C 2 to 4.7 pF . Figure 6 shows the RF input return loss with C 2 set to 4.7 pF . Table 2 shows the impedance and input reflection coefficient for the RF input with $\mathrm{C} 2=0.3 \mathrm{pF}$. The input transmission line length is de-embedded from the measurement.

Table 2. RF Input Impedance

| FREQUENCY <br> (MHz) | S11 |  |  |
| :---: | :---: | :---: | :---: |
|  |  | MAG | ANGLE ( ${ }^{\circ}$ ) |
| 300 | $24.9+j 27.6$ | 0.468 | 112.0 |
| 400 | $39.1+j 37.3$ | 0.403 | 83.5 |
| 500 | $60.1+j 36.9$ | 0.330 | 56.2 |
| 700 | $77.4-\mathrm{j} 1.9$ | 0.215 | -3.2 |
| 1000 | $43.7-\mathrm{j} 19.2$ | 0.211 | -96.7 |
| 1500 | $27.2-\mathrm{j} 2.1$ | 0.297 | -173.2 |
| 2000 | $29.6+\mathrm{j} 14.5$ | 0.310 | 134.4 |
| 2500 | $39.3+\mathrm{j} 26.0$ | 0.303 | 96.0 |
| 3000 | $48.9+\mathrm{j} 23.1$ | 0.228 | 79.9 |
| 3500 | $52.4+\mathrm{j} 19.2$ | 0.185 | 72.3 |
| 4000 | $60.5+\mathrm{j} 8.2$ | 0.120 | 33.8 |
| 4500 | $69.2+\mathrm{j} 15.0$ | 0.202 | 30.8 |
| 5000 | $82.4+\mathrm{j} 11.5$ | 0.259 | 14.6 |
| 5500 | $71.2-\mathrm{j} 8.6$ | 0.188 | -18.0 |
| 6000 | $46.8-\mathrm{j} 13.1$ | 0.138 | -96.1 |

## LO Input Port

The demodulator's LO input interface is shown in Figure 7. The input consists of a programmable input match and a high precision quadrature phase shifter which generates $0^{\circ}$ and $90^{\circ}$ phase shifted LO signals for the LO buffer amplifiers to drive the I/Q mixers. DC blocking capacitors are required on the LOP and LOM inputs. When using a


Figure 5. RF Input Return Loss


Figure 6. RF Input Return Loss with C2 $=4.7 \mathrm{pF}$


Figure 7. Simplified Schematic of the LO Inputs with Single-Ended Drive

## APPLICATIONS INFORMATION

single-ended LO input, it is necessary to terminate the unused LO input (LOP in Figure 7) into $50 \Omega$.

The programmable input match adjust is controlled by the BAND, CF1, LF1, and CF2 registers as detailed in the


Figure 8. Single-Ended LO Input Return Loss vs BAND, CF1, LF1, and CF2
register map shown in Table 3. The return loss for the register setting in Table 3 is shown in Figure 8.

Table 3. Register Settings for Single-Ended LO Matching

| LO FREQUENCY (MHz) | BAND | CF1 | LF1 | CF2 |
| :---: | :---: | :---: | :---: | :---: |
| $300-339$ | 0 | 31 | 3 | 31 |
| $339-398$ | 0 | 21 | 3 | 24 |
| $398-419$ | 0 | 14 | 3 | 23 |
| $419-556$ | 0 | 17 | 2 | 31 |
| $556-625$ | 0 | 10 | 2 | 23 |
| $625-801$ | 0 | 15 | 1 | 31 |
| $801-831$ | 0 | 14 | 1 | 27 |
| $831-1046$ | 0 | 8 | 1 | 21 |
| $1046-1242$ | 1 | 31 | 3 | 31 |
| $1242-1411$ | 1 | 21 | 3 | 28 |
| $1411-1696$ | 1 | 17 | 2 | 26 |
| $1696-2070$ | 1 | 15 | 1 | 31 |
| Default | 1 | 8 | 3 | 3 |
| $2070-2470$ | 1 | 8 | 1 | 21 |
| $2470-2980$ | 1 | 2 | 1 | 10 |
| $2980-3500$ | 1 | 1 | 0 | 19 |
| $3500-6000$ | 1 | 0 | 0 | 0 |

The LO inputs can also be driven differentially. Figure 10 compares the uncalibrated OIP2 performance of single ended versus differential LO drive using the ANAREN B4859A53 balun as shown in the schematic of Figure 9.


Figure 9. Simplified Schematic of the LO Inputs Using a Balun for Differential Drive


Figure 10. OIP2 vs Single-Ended and Differential LO Input

## APPLICATIONS InFORMATION

## Interstage Filter

An interstage IF filter should be used between the MIP (MIM) and AIP (AIM) pins and the MQP (MQM) and AQP (AQM) pins to suppress the large $f_{R F}+f_{L O}$ and other mixing products from the mixer outputs. Without the filter, the linearity of the amplifier can be degraded for the desired signal. Figure 11 shows a recommended lowpass filter. Table 4 shows typical values used for a lowpass response of various bandwidths.

Table 4. Component Values for Interstage Lowpass Filter

| 1dB BW (MHz) | L1, L2 (nH) | C9, C11 (pF) | C10, C12 (pF) |
| :---: | :---: | :---: | :---: |
| 20 | 330 | 39 | 120 |
| 50 | 150 | 15 | 47 |
| 100 | 68 | 10 | 22 |
| 300 | 33 | 4.7 | 6.8 |
| 500 | 22 | 3.0 | 3.0 |
| 1000 | 8 | 0.5 | 1.0 |

It is important that the placement of C 10 and C 12 be as close as possible to the amplifier inputs. Long line
lengths on the amplifier inputs can lead to instability. As shown in Figure 12, a $50 \Omega$ common-mode termination resistor can be used to better ensure stability with long line lengths and/or higher order filtering. The placement of $\mathrm{C9}$ and C 11 should be as close as possible to the mixer outputs for effective filtering of the $2 x L 0, f_{R F}+f_{\text {LO }}$, and other mixing products.


Figure 12. Interstage IF Filter with Common-Mode Termination
By adjusting the values of the capacitors in the filter, it is possible to add or remove frequency slope of the IF


Figure 11. Simplified Schematic of the Mixer Output and IF Amplifier Input with Interstage Filter

## APPLICATIONS INFORMATION

response. The RF input has a frequency slope above 2 GHz of approximately $-2 \mathrm{~dB} / \mathrm{GHz}$. If a high-side LO (HSLO) is used the resulting IF slope will be $2 \mathrm{~dB} / \mathrm{GHz}$. If a low-side LO (LSLO) is used the resulting IF slope will be $-2 \mathrm{~dB} / \mathrm{GHz}$. The IF filter component values can be adjusted so that approximately 1 dB of peaking or roll-off can be achieved over the filter bandwidth to give an overall flat IF response for the HSLO or LSLO case.

## I-Channel and Q-Channel Outputs

The phase relationship between the I-channel output signal and the Q-channel output signal is fixed. When the LO input frequency is higher (or lower) than the RF input frequency, the Q-channel outputs (IFQP, IFQM) lead (or lag) the I-channel outputs (IFIP, IFIM) by $90^{\circ}$.
Figure 14 shows a simplified schematic of the IF amplifier outputs. The current-mode outputs require a terminating resistance to establish a common-mode voltage level. The optimum operating current is 18 mA per output. A $50 \Omega$ termination to ground is recommended on each output for a 0.9 V common-mode voltage. Operation at higher or lower common-mode voltages is possible with the addition of a common-mode termination. For example, to operate at 1.8 V , an additional common-mode resistance of $25 \Omega$ ( $\mathrm{R} 5=66.5 \Omega$ and $\mathrm{R} 6=0 \Omega$, or $\mathrm{R} 5=\mathrm{R} 6=43.2 \Omega$ ) would be used to maintain an output current of 18 mA . Alternatively, a $100 \Omega$ termination to ground on each output can be used


Figure 13. OIP3 of Amplifier Only vs Output Common-Mode Voltage (VCM)
for 1.8 V common-mode voltage with 6dB more conversion gain. To operate at lower common-mode voltages, a lower termination resistance can be used on each output at the expense of conversion gain, or a negative supply can be used at the connection of the termination resistors. Figure 13 shows the OIP3 of the amplifier alone with various common-mode voltages.
The amplifier gain can be adjusted in 8 steps of roughly 1 dB from 8 dB to 15 dB using the AMPG register. Setting AMPG $=0 \times 7$ sets the gain at about 15 dB and setting AMPG $=0 \times 0$ sets the gain to about 8 dB .


Figure 14. Simplified Schematic of the IF Amplifier Output with Anti-Alias Filter

## APPLICATIONS InFORMATION

A typical anti-alias filter is shown in Figure 14 for interface with an ADC. The parallel combinations R3||R7 and R4||R8 set the differential impedance for the ADC. The input and output of the filter contain a common-mode termination for high frequencies. These are formed by C 17 , C18 and $24.9 \Omega$ at the input and C23, C24 and $24.9 \Omega$ at the output. The common-mode termination at the amplifier output ensures stability and the common-mode termination at the ADC input provides a termination for the high-frequency kickback from the sampling capacitors in the ADC. Table 5 shows some typical values vs 1 dB cutoff frequency for the anti-alias filter. To optimize the flatness and ripple of the IF band, both the IF interstage filter and the anti-alias filter can be designed together in a simulator including package parasitics. The additional slope due to RF slope and HSLO or LSLO can be compensated by using this method. The layout of the anti-alias filter should be done so that the amplifier outputs and ADC inputs are as close as possible. This is to prevent long line lengths from introducing additional parasitics.

Table 5. Component Values for Anti-Alias Lowpass Filter

| $\mathbf{1 d B}$ BW <br> $\mathbf{( M H z )}$ | L5-L8 <br> $\mathbf{( n H )}$ | C17, C18 <br> $\mathbf{( p F )}$ | C20, C21 <br> $\mathbf{( p F )}$ | C23, C24 <br> $\mathbf{( \mathbf { p F } )}$ |
| :---: | :---: | :---: | :---: | :---: |
| 20 | 560 | 56 | 180 | 82 |
| 50 | 240 | 22 | 68 | 33 |
| 100 | 120 | 12 | 39 | 22 |
| 300 | 33 | 3.9 | 8.2 | 6.8 |
| 500 | 22 | 1.8 | 6.8 | 3.3 |
| 1000 | 8 | 1.0 | 3.3 | 1.8 |

Table 6 and Table 7 show the differential and commonmode S-parameters for the amplifier by itself with $50 \Omega$ terminations on all ports. In addition, common-mode terminations were used on the input and output ports having a value of 2 pF in series with $50 \Omega$.

Table 6. IF Amplifier S-Parameters (Differential-Mode)

| IF | $\mathbf{S}_{11}$ |  | $\mathbf{S}_{21}$ |  | $\mathbf{S}_{12}$ |  | $\mathbf{S}_{22}$ |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| (MHz) | MAG | ANG | MAG | ANG | MAG | ANG | MAG | ANG |
| 0.001 | 0.204 | -179.9 | 2.129 | 180.0 | $1.8 \mathrm{e}-4$ | 164.8 | 0.014 | 178.5 |
| 100 | 0.203 | 176.0 | 2.154 | 171.9 | $5.4 \mathrm{e}-4$ | 118.0 | 0.026 | -120.9 |
| 200 | 0.205 | 172.2 | 2.170 | 163.7 | $1.0 \mathrm{e}-4$ | 102.8 | 0.050 | -112.0 |
| 300 | 0.207 | 168.5 | 2.197 | 155.6 | $1.7 \mathrm{e}-4$ | 92.8 | 0.079 | -113.5 |
| 400 | 0.210 | 164.8 | 2.239 | 147.3 | $2.8 \mathrm{e}-4$ | 93.7 | 0.111 | -118.3 |
| 500 | 0.215 | 160.9 | 2.292 | 138.8 | $3.2 \mathrm{e}-4$ | 95.4 | 0.147 | -125.0 |
| 600 | 0.221 | 157.0 | 2.363 | 130.1 | $4.0 \mathrm{e}-4$ | 92.0 | 0.186 | -132.1 |
| 700 | 0.227 | 153.0 | 2.445 | 121.2 | $5.0 \mathrm{e}-4$ | 92.1 | 0.230 | -140.0 |
| 800 | 0.235 | 149.0 | 2.535 | 112.0 | $5.5 \mathrm{e}-4$ | 86.2 | 0.279 | -148.1 |
| 900 | 0.242 | 144.6 | 2.642 | 102.0 | $6.9 \mathrm{e}-4$ | 93.2 | 0.334 | -157.0 |
| 1000 | 0.251 | 140.6 | 2.770 | 92.3 | $7.9 \mathrm{e}-4$ | 92.7 | 0.396 | -166.2 |
| 1500 | 0.303 | 117.6 | 3.420 | 32.3 | 0.003 | 92.6 | 0.738 | 134.4 |
| 2000 | 0.365 | 90.2 | 3.318 | -45.5 | 0.005 | 33.2 | 0.828 | 70.0 |
| 2500 | 0.385 | 56.1 | 2.232 | -105.2 | 0.005 | -3.1 | 0.666 | 13.1 |
| 3000 | 0.365 | 16.6 | 2.620 | -160.2 | 0.005 | -34.2 | 0.488 | -38.4 |
| 3500 | 0.319 | -28.2 | 1.021 | 157.4 | 0.005 | -61.9 | 0.418 | -94.7 |
| 4000 | 0.307 | -83.4 | 0.742 | 113.3 | 0.005 | -79.5 | 0.409 | -150.6 |

Table 7. IF Amplifier S-Parameters (Common-Mode)

| IF | $\mathbf{S}_{11}$ |  | $\mathbf{S}_{21}$ |  | $\mathbf{S}_{12}$ |  | $\mathbf{S}_{22}$ |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| (MHz) | MAG | ANG | MAG | ANG | MAG | ANG | MAG | ANG |
| 0.001 | 0.184 | -138.7 | $9.2 e-4$ | -112.8 | 0.037 | -65.3 | 0.985 | 179.8 |
| 100 | 0.186 | 172.5 | 0.085 | -118.9 | 0.013 | -68.6 | 0.152 | 126.7 |
| 200 | 0.188 | 166.6 | 0.173 | -134.7 | 0.007 | -91.8 | 0.125 | 116.7 |
| 300 | 0.191 | 160.2 | 0.237 | -150.0 | 0.004 | -113.1 | 0.097 | 97.3 |
| 400 | 0.196 | 154.4 | 0.291 | -163.8 | 0.002 | -145.4 | 0.067 | 75.2 |
| 500 | 0.202 | 148.4 | 0.340 | -176.8 | 0.002 | 170.2 | 0.037 | 43.6 |
| 600 | 0.210 | 142.8 | 0.387 | 170.9 | 0.002 | 137.0 | 0.023 | -38.0 |
| 700 | 0.219 | 137.2 | 0.436 | 159.1 | 0.003 | 118.1 | 0.051 | -97.8 |
| 800 | 0.230 | 132.0 | 0.488 | 147.1 | 0.003 | 107.8 | 0.094 | -121.5 |
| 900 | 0.243 | 126.5 | 0.550 | 134.9 | 0.004 | 106.6 | 0.148 | -137.0 |
| 1000 | 0.252 | 120.9 | 0.612 | 122.2 | 0.006 | 104.8 | 0.211 | -151.3 |
| 1500 | 0.325 | 96.7 | 0.981 | 43.4 | 0.020 | 80.4 | 0.749 | 136.1 |
| 2000 | 0.438 | 72.1 | 0.776 | -46.1 | 0.036 | 18.6 | 1.000 | 55.9 |
| 2500 | 0.549 | 40.1 | 0.496 | -97.1 | 0.041 | -21.9 | 0.873 | 2.9 |
| 3000 | 0.601 | 6.9 | 0.397 | -143.2 | 0.042 | -52.2 | 0.764 | -37.3 |
| 3500 | 0.618 | -27.5 | 0.281 | -175.7 | 0.044 | -80.3 | 0.668 | -72.7 |
| 4000 | 0.595 | -60.3 | 0.254 | 147.3 | 0.046 | -101.2 | 0.620 | -107.0 |

## APPLICATIONS InFORMATION

The common-mode feedback amplifier holds the com-mon-mode output voltage within about 20 mV of the VCM pin voltage. The VCM pin interface is shown in Figure 15. The VCM pin should be driven by a voltage source with an output impedance lower than $1 \mathrm{k} \Omega$. When the VCM pin is unbiased, the output common-mode voltage will be held at a nominal 0.9 V given by the internal voltage divider formed by the $40 \mathrm{k} \Omega$ and $8 \mathrm{k} \Omega$ resistors. Connecting the VCM pin to an ADC common-mode reference pin allows the output common-mode voltage of the IF amplifier to track the ADC common-mode.


Figure 15. Simplified Schematic of the VCM Input Pin

## Temperature Diode

A schematic of the TEMP pin is shown in Figure 16. The temperature diode can be used to directly measure the die temperature. $\mathrm{A} 40 \mathrm{k} \Omega$ resistor is recommended to $\mathrm{V}_{\text {CC }}$ to generate a $100 \mu \mathrm{~A}$ current source for the diode readout. The temperature slope is about $-1.52 \mathrm{mV} /{ }^{\circ} \mathrm{C}$.


Figure 16. Schematic of the TEMP Pin

## Digital Input Pins

Figure 17 show the simplified schematics for the digital input pins, SCK, CSB, SDI, and RFSW. These pins should not be left floating, since there is no internal pull-down or pull-up.


Figure 17. Simplified Schematic of the Digital Input Pins (SCK, CSB, SDI, RFSW)

## OVDD Interface

Figure 18 shows the simplified schematic of the OVDD interface. The OVDD pin supplies the voltage for the digital inputs and SDO pin. By setting the pin at 1.2 V to 3.3 V , the serial port can function with 1.2 V to 3.3 V logic levels. It is important that when sequencing the supply voltages for the chip that the VCC supply be brought up first before the OVDD supply. This is to prevent the ESD diode connected between OVDD and VCC from getting damaged.


Figure 18. Simplified Schematic of the OVDD Pin Interface

## APPLICATIONS INFORMATION

## SERIAL PORT

The SPI-compatible serial port provides control and monitoring functionality.

## Communication Sequence

The serial bus is comprised of CSB, SCK, SDI and SDO. Data transfers to the part are accomplished by the serial bus master device first taking CSB low to enable the LTC5586's port. Input data applied on SDI is clocked on the rising edge of SCK, with all transfers MSB first. The communication burst is terminated by the serial bus master returning CSB high. See the Timing Diagrams for details.

Data is read from the part during a communication burst using SDO. Readback may be multidrop (more than one LTC5586 or other serial device connected in parallel on the serial bus), as SDO is high impedance ( $\mathrm{Hi}-\mathrm{Z}$ ) when $C S B=1$.

## Single Byte Transfers

The serial port is arranged as a simple memory map, with status and control available in 23 registers as shown in the appendix. All data bursts are comprised of at least two 8-bit bytes. The most significant bit of the first byte is the read/write bit. Setting this bit to 1 puts the serial port into read mode. The next 7 bits of the first byte are address bits and can be set from $0 \times 00$ to $0 \times 17$. The subsequent byte, or bytes, is data from/to the specified register address. See the Timing Diagrams for details. Note that the written data is transferred to the internal register at the falling edge of the $16^{\text {th }}$ clock cycle (parallel load).

## Multiple Byte Transfers

More efficient data transfer of multiple bytes is accomplished by using the LTC5586's register address autoincrement feature as shown in the Timing Diagrams. The serial port master sends the destination register address in the first byte and reads or writes data in the second byte as before, but on the third byte the address pointer is auto-incremented by 1 and the serial port master can read or write to subsequent registers. If the register address pointer attempts to increment past 23 (0x17), it is automatically reset to 0 .

## SDO_MODE Control Bit

The SDO output has two modes of operation as shown in the Timing Diagrams. When register $0 \times 16$ control bit SDO_MODE = 0, the SDO pin functions as a normal output which is High-Z during a write command. If SDO_MODE $=1$, the SDO output is put into a serial repeater mode where SDO echoes the command written to SDI before readback of register contents either in read or write mode. This can be used in high bus noise environments where it is necessary to perform error-checking on commands sent to the serial port.

A simplified schematic of the SDO output is shown in Figure 19. The OVDD supply sets the logic level of the output, and a $25 \Omega$ series resistor limits the output current.


Figure 19. Simplified Schematic of the SDO Pin Interface

## Register Defaults

The register map and defaults are given in Table 8 and 9 in the appendix. When the device is powered up, the registers may not be reset to their default values. By writing a 1 to the SRST bit (bit[3]) of register 0x16, the device will go into soft reset and the registers will be reset to their default values.

## APPLICATIONS INFORMATION

## Impairment Minimization

The LTC5586 contains circuitry for minimizing receiver impairments such as DC offset, Phase and Gain Error, and non-linearity. An example block diagram of a DPD transmitter application is shown in Figure 20. A DSP is used to implement a 2-tone source and minimization algorithms for calibration of impairments. To setup the DSP for impairment calibration, the DATA ENCODER would be configured to produce symbols for two tones in the band of interest. The tones would be modulated up to the carrier frequency of $f_{\text {LO }}$ before being applied to the LTC5586 RFA input. The tones are then down-converted to baseband for the DSP.

In the DSP, a complex-FFT can be used to extract gain error and phase error for image rejection optimization, while the FFT of each channel can be used to optimize DC offset and nonlinearities independently. One possible general optimization method would be to sequentially apply a 1-D minimization algorithm to each impairment. A simple bisection method or more complicated (but faster converging) Brent's method[1] could be used for the 1-D minimization.

Figure 21 shows the non-optimized spectrum and Figure 22 shows the optimized spectrum for a 2-tone test signal at 2 GHz . The Upper Sideband spectrum is the desired signal while the Lower Sideband is the image signal.
[1] Saul Teukolsky, William T. Vetterling, William H. Press, and Brian P. Flannery, "Numerical Recipes in C: The Art of Scientific Computing," p. 352, 1988.


Figure 20. Example Block Diagram of a DPD Transmitter with DSP for Impairment Minimization

## LTC5586

## APPLICATIONS InFORMATION



Figure 21. Non-Optimized 2-Tone Spectrum at 2GHz with 100MHz Anti-Alias Filter

## APPLICATIONS InFORMATION



Figure 22. Optimized 2-Tone Spectrum at 2GHz with 100MHz Anti-Alias Filter

## LTC5586

## APPERDIX

Table 8. Serial Port Register Contents

| ADDR | MSB | [6] | [5] | [4] | [3] | [2] | [1] | LSB | R/W | DEFAULT |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| 0x00 | IM3QY[7] | IM3QY[6] | IM3QY[5] | IM3QY[4] | IM3QY[3] | IM3QY[2] | IM3QY[1] | IM3QY[0] | R/W | 0x80 |
| $0 \times 01$ | IM3QX[7] | IM3QX[6] | IM3QX[5] | IM3QX[4] | IM3QX[3] | IM3QX[2] | IM3QX[1] | IM3QX[0] | R/W | $0 \times 80$ |
| 0x02 | IM3IY[7] | IM3IY[6] | IM3IY[5] | IM3IY[4] | IM3IY[3] | IM3IY[2] | IM3IY[1] | IM3IY[0] | R/W | 0x80 |
| 0x03 | IM3IX[7] | IM3IX[6] | IM3IX[5] | IM3IX[4] | IM3IX[3] | IM3IX[2] | IM3IX[1] | IM3IX[0] | R/W | 0x80 |
| 0x04 | IM2QX[7] | IM2QX[6] | IM2QX[5] | IM2QX[4] | IM2QX[3] | IM2QX[2] | IM2QX[1] | IM2QX[0] | R/W | 0x80 |
| 0x05 | IM2IX[7] | IM2IX[6] | IM2IX[5] | IM2IX[4] | IM2IX[3] | IM2IX[2] | IM2IX[1] | IM2IX[0] | R/W | 0x80 |
| 0x06 | HD3QY[7] | HD3QY[6] | HD3QY[5] | HD3QY[4] | HD3QY[3] | HD3QY[2] | HD3QY[1] | HD3QY[0] | R/W | 0x80 |
| 0x07 | HD3QX[7] | HD3QX[6] | HD3QX[5] | HD3QX[4] | HD3QX[3] | HD3QX[2] | HD3QX[1] | HD3QX[0] | R/W | 0x80 |
| 0x08 | HD3IY[7] | HD3IY[6] | HD3IY[5] | HD3IY[4] | HD3IY[3] | HD3IY[2] | HD3IY[1] | HD3IY[0] | R/W | 0x80 |
| 0x09 | HD3IX[7] | HD3IX[6] | HD3IX[5] | HD3IX[4] | HD3IX[3] | HD3IX[2] | HD3IX[1] | HD3IX[0] | R/W | 0x80 |
| 0x0A | HD2QY[7] | HD2QY[6] | HD2QY[5] | HD2QY[4] | HD2QY[3] | HD2QY[2] | HD2QY[1] | HD2QY[0] | R/W | 0x80 |
| Ox0B | HD2QX[7] | HD2QX[6] | HD2QX[5] | HD2QX[4] | HD2QX[3] | HD2QX[2] | HD2QX[1] | HD2QX[0] | R/W | $0 \times 80$ |
| OxOC | HD2IY[7] | HD2IY[6] | HD2IY[5] | HD2IY[4] | HD2IY[3] | HD2IY[2] | HD2IY[1] | HD2IY[0] | R/W | 0x80 |
| OxOD | HD2IX[7] | HD2IX[6] | HD2IX[5] | HD2IX[4] | HD2IX[3] | HD2IX[2] | HD2IX[1] | HD2IX[0] | R/W | 0x80 |
| OxOE | DCOI[7] | DCOI[6] | DCOI[5] | DCOI[4] | DCOI[3] | DCOI[2] | DCOI[1] | DCOI[0] | R/W | 0x80 |
| 0x0F | DCOQ[7] | DCOQ[6] | DCOQ[5] | DCOQ[4] | DCOQ[3] | DCOQ[2] | DCOQ[1] | DCOQ[0] | R/W | 0x80 |
| $0 \times 10$ | ATT[4] | ATT[3] | ATT[2] | ATT[1] | ATT[0] | IP3IC[2] | IP3IC[1] | IP3IC[0] | R/W | 0x04 |
| $0 \times 11$ | GERR[5] | GERR[4] | GERR[3] | GERR[2] | GERR[1] | GERR[0] | IP3CC[1] | IP3CC[0] | R/W | 0x82 |
| $0 \times 12$ | LVCM[2] | LVCM[1] | LVCM[0] | CF1[4] | CF1[3] | CF1[2] | CF1[1] | CF1[0] | R/W | 0x48 |
| $0 \times 13$ | BAND | LF1[1] | LF1[0] | CF2[4] | CF2[3] | CF2[2] | CF2[1] | CF2[0] | R/W | 0xE3 |
| 0x14 | PHA[8] | PHA[7] | PHA[6] | PHA[5] | PHA[4] | PHA[3] | PHA[2] | PHA[1] | R/W | 0x80 |
| $0 \times 15$ | PHA[0] | AMPG[2] | AMPG[1] | AMPG[0] | AMPCC[1] | AMPCC[0] | AMPIC[1] | AMPIC[0] | R/W | $0 \times 6 \mathrm{~A}$ |
| $0 \times 16$ | 1* | 1* | 1* | 1* | SRST | SDO_MODE | 0* | 0* | R/W | 0xF0 |
| 0x17 | CHIPID[1] | CHIPID[0] | 0 * | $0 *$ | 0 * | 0 * | 0* | RFSW | R/W | 0x01 |

*Unused, do not change default value.

## APPERDIX

Table 9. Serial Port Register Bit Field Summary

| BITS | FUNCTION | DESCRIPTION | VALID VALUES | DEFAULT |
| :---: | :---: | :---: | :---: | :---: |
| AMPCC[1:0] | IF Amplifier IM3 CC Adjust | Used to optimize the IF amplifier IM3. | 0x00 to 0x03 | 0x02 |
| AMPIC[1:0] | IF Amplifier IM3 IC Adjust | Used to optimize the IF amplifier IM3. | 0x00 to 0x03 | 0x02 |
| AMPG[2:0] | IF Amplifier Gain Adjust | Adjusts the amplifier gain from 8dB to 15dB. | 0x00 to 0x07 | $0 \times 06$ |
| ATT[4:0] | Step Attenuator Control | Controls the step attenuator from 0 dB to 31 dB attenuation. | 0x00 to 0x1F | $0 \times 00$ |
| BAND | LO Band Select | Selects which LO matching band is used. BAND $=1$ for high band. BAND = 0 for low band. | 0,1 | 1 |
| CF1[5:0] | L0 Matching Capacitor CF1 | Controls the CF1 capacitor in the LO matching network. | 0x00 to 0x1F | 0x08 |
| CF2[5:0] | LO Matching Capacitor CF2 | Controls the CF2 capacitor in the LO matching network. | 0x00 to 0x1F | $0 \times 03$ |
| CHIPID | Chip Identification Bits | Factory set to default value. | 0x00 to 0x03 | $0 \times 00$ |
| DCOI[7:0] | I-Channel DC Offset | Controls the I-channel DC offset over a range from -200mV to 200 mV . | Ox00 to 0xFF | $0 \times 80$ |
| DCOQ[7:0] | Q-Channel DC Offset | Controls the Q-channel DC offset over a range from -200mV to 200 mV . | 0x00 to 0xFF | $0 \times 80$ |
| GERR[5:0] | IQ Gain Error Adjust | Controls the IQ gain error over a range from -0.5 dB to 0.5 dB . | 0x00 to 0x3F | 0x20 |
| HD2IX[7:0] | HD2 I-Channel X-Vector | Controls the I-channel HD2 X-vector adjustment. | 0x00 to 0xFF | 0x80 |
| HD2IY[7:0] | HD2 I-Channel Y-Vector | Controls the I-channel HD2 Y-vector adjustment. | Ox00 to 0xFF | $0 \times 80$ |
| HD2QX[7:0] | HD2 Q-Channel X-Vector | Controls the Q-channel HD2 X-vector adjustment. | Ox00 to 0xFF | $0 \times 80$ |
| HD2QY[7:0] | HD2 Q-Channel Y-Vector | Controls the Q-channel HD2 Y-vector adjustment. | 0x00 to 0xFF | $0 \times 80$ |
| HD3IX[7:0] | HD3 I-Channel X-Vector | Controls the I-channel HD3 X-vector adjustment. | Ox00 to 0xFF | 0x80 |
| HD3IY[7:0] | HD3 I-Channel Y-Vector | Controls the I-channel HD3 Y-vector adjustment. | 0x00 to 0xFF | 0x80 |
| HD3QX[7:0] | HD3 Q-Channel X-Vector | Controls the Q-channel HD3 X-vector adjustment. | Ox00 to 0xFF | 0x80 |
| HD3QY[7:0] | HD3 Q-Channel Y-Vector | Controls the Q-channel HD3 Y-vector adjustment. | 0x00 to 0xFF | 0x80 |
| IM21X[7:0] | IM2 I-Channel X-Vector | Controls the I-channel IM2 X-vector adjustment. | 0x00 to 0xFF | 0x80 |
| IM2QX[7:0] | IM2 Q-Channel X-Vector | Controls the Q-channel IM2 X-vector adjustment. | Ox00 to 0xFF | $0 \times 80$ |
| IM3IX[7:0] | IM3 I-Channel X-Vector | Controls the I-channel IM3 X-vector adjustment. | 0x00 to 0xFF | 0x80 |
| IM31Y[7:0] | IM3 I-Channel Y-Vector | Controls the I-channel IM3 Y-vector adjustment. | 0x00 to 0xFF | $0 \times 80$ |
| IM3QX[7:0] | IM3 Q-Channel X-Vector | Controls the Q-channel IM3 X-vector adjustment. | 0x00 to 0xFF | 0x80 |
| IM3QY[7:0] | IM3 Q-Channel Y-Vector | Controls the Q-channel IM3 Y-vector adjustment. | 0x00 to 0xFF | 0x80 |
| IP3CC[1:0] | RF Input IP3 CC Adjust | Used to optimize the RF input IP3. | 0x00 to 0x03 | $0 \times 02$ |
| IP3IC[2:0] | RF Input IP3 IC Adjust | Used to optimize the RF input IP3. | 0x00 to 0x07 | 0x04 |
| LF1[1:0] | L0 Matching Inductor LF1 | Controls the LF1 inductor in the LO matching network. | 0x00 to 0x03 | $0 \times 03$ |
| LVCM[2:0] | LO Bias Adjust | Used to optimize mixer IP3. | 0x00 to 0x07 | $0 \times 02$ |
| PHA[8:0] | IQ Phase Error Adjust | Controls the IQ phase error over a range from -2.5 Degrees to 2.5 Degrees. | 0x000 to 0x1FF | 0x100 |
| RFSW | RF Switch Input Select | Controls the RF switch state with a logical AND of the RFSW pin. | 0, 1 | 1 |
| SDO_MODE | SDO Readback Mode | Enables the SDO readback mode if SDO_MODE $=1$. | 0,1 | 0 |
| SRST | Soft Reset | Writing 1 to this bit resets all registers to their default values. | 0, 1 | 0 |

## LTC5586

PACKAGE DESCRIPTION

## UH Package

32-Lead Plastic QFN ( $5 \mathrm{~mm} \times 5 \mathrm{~mm}$ )
(Reference LTC DWG \# 05-08-1693 Rev D)


RECOMMENDED SOLDER PAD LAYOUT APPLY SOLDER MASK TO AREAS THAT ARE NOT SOLDERED



NOTE:
$\longleftarrow 0.50$ BSC
. DRAWING PROPOSED TO BE A JEDEC PACKAGE OUTLINE M0-220 VARIATION WHHD-(X) (TO BE APPROVED)
2. DRAWING NOT TO SCALE
3. ALL DIMENSIONS ARE IN MILLIMETERS
4. DIMENSIONS OF EXPOSED PAD ON BOTTOM OF PACKAGE DO NOT INCLUDE MOLD FLASH. MOLD FLASH, IF PRESENT, SHALL NOT EXCEED 0.20 mm ON ANY SIDE
5. EXPOSED PAD SHALL BE SOLDER PLATED
6. SHADED AREA IS ONLY A REFERENCE FOR PIN 1 LOCATION ON THE TOP AND BOTTOM OF PACKAGE

## revision history

| REV | DATE | DESCRIPTION | PAGE NUMBER |
| :---: | :---: | :--- | :---: |
| A | $08 / 17$ | Various corrections. | $5,7,14,21,23,32$ |
| B | $07 / 18$ | $\mathrm{~T}_{\mathrm{J}}=25^{\circ} \mathrm{C}$ | 5,7 |

## LTC5586

## TYPICAL APPLICATION

Simplified Schematic of a 0.3GHz to 6.0GHz Receiver, (Only I-Channel Is Shown)


## RELATED PARTS

| PART NUMBER | DESCRIPTION | COMMENTS |
| :---: | :---: | :---: |
| Infrastructure |  |  |
| LTC5569 | 300MHz to 4GHz Dual Active Downconverting Mixer | 2dB Gain, 26.7dBm IIP3 and 11.7dB NF at 1950MHz, 3.3V/180mA Supply |
| LTC6409 | 10GHz GBW Differential Amplifier | DC-Coupled, 48dBm OIP3 at 140MHz, 1.1nV/ $\sqrt{\mathrm{Hz}}$ Input Noise Density |
| LTC5549 | 2GHz to 14GHz Mixer with Integrated LO Doubler | Ultra-Wideband Bidirectional Up-, or Down-Conversion Mixer, +22.8 dBm IIP3 at 12 GHz , 0 dBm LO Drive, 500 MHz to 6 GHz IF Bandwidth |
| LTC5548 | 2GHz to 14GHz Mixer with IF Frequency Extending to DC | Ultra-Wideband Bidirectional Up-, or Down-Conversion Mixer, +18.7 dBm IIP3 at 12GHz, OdBm LO Drive with On-Chip Frequency Doubler, DC to 6GHz IF Bandwidth |
| LTC5588-1 | 200MHz to 6GHz Quadrature Modulator | +31dBm OIP3, $-160 \mathrm{dBm} / \mathrm{Hz}$ Output Noise Floor, Excellent ACPR Performance |
| RF PLL/Synthesizer with VCO |  |  |
| LTC6946-3 | Low Noise, Low Spurious Integer-N PLL with Integrated VCO | 640MHz to $5.79 \mathrm{GHz},-157 \mathrm{dBc} / \mathrm{Hz}$ WB Phase Noise Floor, $-100 \mathrm{dBc} / \mathrm{Hz}$ Closed-Loop Phase Noise |
| LTC6948 | Ultralow Noise Fractional-N Synthesizer with Integrated VCO | 370MHz to 6.39GHz PLL, No Delta-Sigma Modulator Spurs, 18-Bit Fractional Denominator, $-226 \mathrm{dBc} / \mathrm{Hz}$ Normalized In-Band Phase Noise Floor |
| ADCs |  |  |
| LTC2145-14 | 14-Bit, 125Msps 1.8V Dual ADC | 73.1dB SNR, 90dB SFDR, 95mW/Ch Power Consumption |
| LTC2185 | 16-Bit, 125Msps 1.8V Dual ADC | 76.8 dB SNR, 90dB SFDR, 185mW/Channel Power Consumption |
| LTC2158-14 | 14-Bit, 310Msps 1.8V Dual ADC, 1.25GHz FullPower Bandwidth | 68.8dB SNR, 88dB SFDR, 362mW/Ch Power Consumption, 1.32VP-p Input Range |

## X-ON Electronics

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[^0]:    Consult ADI Marketing for parts specified with wider operating temperature ranges.

